

Abstract of the Disclosure (FIG. 3)

"A SUBSTRATE CLEANING METHOD AND
A SUBSTRATE CLEANING APPARATUS"

The substrate cleaning method for performing
5 cleaning processing on a plurality of substrates
disposed such that front surfaces (Wa) of the
substrates on which a circuit pattern is to be formed
extend substantially in a vertical direction. This
method comprises a step (a) of picking up substrates
10 contained in a cassette (C), all together, from the
cassette (C), a step (b) of making front surfaces (Wa)
of adjacent substrates face each other without bringing
the front surfaces (Wa) into contact with each other,
while making back surfaces (Wb) of adjacent substrates
15 face each other without bringing the back surfaces (Wb)
into contact with each other, the front surfaces (Wa)
of the adjacent substrates being situated with a pitch
interval L_1 interposed therebetween, and the pitch
interval being set to be larger than a pitch interval
20 L_2 interposed between the back surfaces (Wb) of the
adjacent substrates, a step (c) of dipping the
plurality of substrates thus disposed, all together,
into a chemical solution, and a step (d) of making
the chemical solution flow between the front surfaces
25 (Wa) of adjacent substrates of the plurality of
substrates, facing each other, and between the back
surfaces (Wb) of adjacent substrates of the plurality

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REPLACED

of substrates, facing each other.

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